

Abstract of the Disclosure:

A base body is provided, on which a first sealing ring and a second sealing ring are disposed. A substrate is disposed on the sealing rings in such a way that a cavity is formed
5 between the first sealing ring, the second sealing ring, the base body and the substrate. An etching substance can be introduced into the cavity in order to etch clear a conductive layer that has been applied to the substrate. When a conductive layer that has been applied to the substrate back
10 surface has been uncovered, an electrolyte can be introduced into the cavity, making contact with the conductive layer and therefore the substrate back surface.

REL/nt